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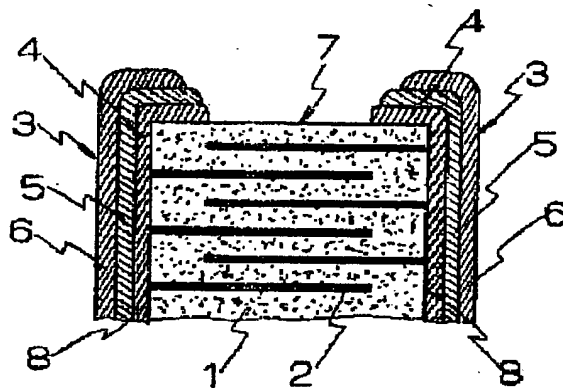
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APPLICANT : HITACHI AIC INC;

INVENTOR : YASUDA TOMIRO;

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TITLE : MULTILAYERED CERAMIC
CAPACITOR



ABSTRACT : PROBLEM TO BE SOLVED: To enhance reliability in soldering a multilayered ceramic capacitor to a wiring board by providing a second outer electrode, composed of a mixture of copper or a copper alloy, nickel or a nickel alloy and an organic adhesive, on a first outer electrode.

SOLUTION: A mixture of silver or a silver palladium alloy, glass and an organic adhesive is applied, as an outer electrode 3, onto the end face 8 of a capacitor element 7 and baked at about 800°C for 30 minutes to form a first outer electrode 4. It is then coated with a mixture of silver clad copper powder having mean grain size of 10μm, silver clad nickel powder and phenol resin based adhesive and baked at about 200°C for 30 minutes to form a second outer electrode 5. Finally, the second outer electrode 5 is subjected to molten solder plating to form a third electrode thus obtaining a multilayer chip ceramic capacitor.

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